

#### **Features**

- High isolation 5000 VRMS
- Peak Breakdown Voltage
  - 250V CT3031, CT3032, CT3033
  - 400V CT3041, CT3042, CT3043
- Operating temperature range 55 °C to 100 °C
- External Creepage ≥ 7.4mm
- Distance Through Isolation ≥ 0.4mm
- Clearance Distance ≥ 7.5mm (S/SL Type)
- Clearance Distance ≥ 8.0mm ( M Type)
- RoHS and REACH Compliance
- Halogen Free Compliance (Optional)
- MSL class 1
- Regulatory Approvals
  - ✓ UL UL1577 (E364000)
  - VDE EN60747-5-5(VDE0884-5)
  - CQC GB4943.1, GB8898
  - IEC60065, IEC60950

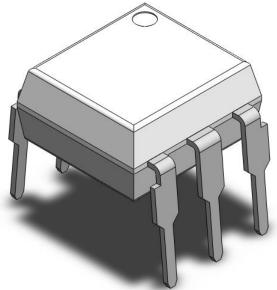
## **Description**

The CT3031, CT3032, CT3033, CT3041, CT3042 and CT3043 consists of a Zero Cross Photo Triac optically coupled to an Infrared-emitting diode in a 6-Pin DIP package DMC-Isolator® with different lead forming options.

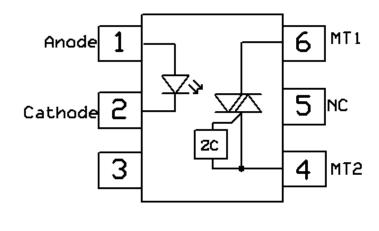
## **Applications**

- Motor Controls
- Lamp ballasts
- Static AC Power Switch
- Solenoid/ Valve Control

## **Package Outline**



## **Schematic**



Note: Different lead forming options available. See package dimension



## Absolute Maximum Ratings $T_A = 25^{\circ}C$ , unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Paramete	Ratings	Units	Notes	
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)		5000	V <sub>RMS</sub>	
Topr	Operating temperature		-55 ~ +100	°C	
Тѕтс	Storage temperature		-55 ~ +150	°C	
TsoL	Soldering temperature (For 10 seconds	s)	260	°C	
Emitter					
l <sub>F</sub>	Forward current	60	mA		
I <sub>F(TRANS)</sub>	Peak transient current (≤1µs P.W,300	1	А		
V <sub>R</sub>	Reverse voltage	6	V		
P <sub>D</sub>	Power dissipation	100	mW		
Detector	•				
P <sub>D</sub>	Power dissipation		300	mW	
		CT3031, CT3032,	250	V	V <sub>DRM</sub>
$V_{DRM}$	Off-State Output Terminal Voltage	CT3033		V	
		CT3041, CT3042,	400	V	
		CT3043		V	
I <sub>TSM</sub>	Peak Repetitive Surge Current		1	А	

## Electrical Characteristics $T_A = 25$ °C (unless otherwise specified)

#### **Emitter Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I <sub>F</sub> =10mA	-	-	1.5	V	
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 6V	-	-	5	μΑ	
Cin	Input Capacitance	f= 1MHz	-	45	-	pF	

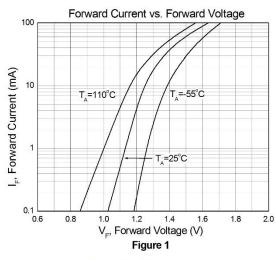
#### **Detector Characteristics**

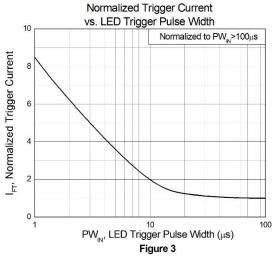
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I <sub>DRM1</sub>	Peak Blocking Current	I <sub>F</sub> = 0mA, V <sub>DRM</sub> = Rated V <sub>DRM</sub>	-	-	100	nA	
I <sub>DRM2</sub>	Inhibit Leakage Current	I <sub>F</sub> = Rated I <sub>FT</sub> , V <sub>DRM</sub> = Rated V <sub>DRM</sub>	-	-	500	μΑ	
VINH	Inhibit Voltage	I <sub>F</sub> = Rated I <sub>FT</sub> ,	-	-	20	V	
V <sub>TM</sub>	Peak On-State Voltage		-	-	3	V	
dv/dt	Critical Rate of Rise off-State	V <sub>PEAK</sub> = Rated V <sub>DRM</sub>	1000	-	-	V/μs	
uv/ut	Voltage	VPEAK= Nateu VDRM					

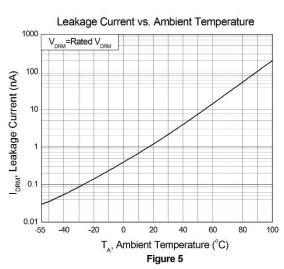
### **Transfer Characteristics**

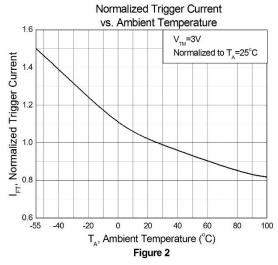
Symbol	Pa	rameters	Test Conditions	Min	Тур	Max	Units	Notes
	Input	CT3031, CT3041	Torminal Valtage 2V	-	-	15		
I <sub>FT</sub>	Trigger	CT3032, CT3042	Terminal Voltage = 3V	-	-	10	mA	
	Current	CT3033, CT3043		-	-	5	1 [	
1	Holding Current		Terminal Voltage from "ON" to "OFF"		270	-	μΑ	
lн	Holding Current	"ON" state I <sub>F</sub> =0mA	-					
Rıo	Isolation Res	istance	V <sub>IO</sub> = 500V <sub>DC</sub> , 40 ~ 60% R.H.	1x10 <sup>11</sup>	ı		Ω	
C <sub>IO</sub>	Isolation Cap	acitance	f= 1MHz	-	0.25	-	pF	

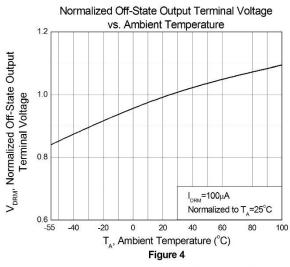
## Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified (Continued)

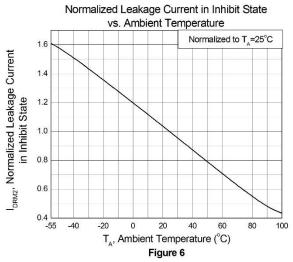




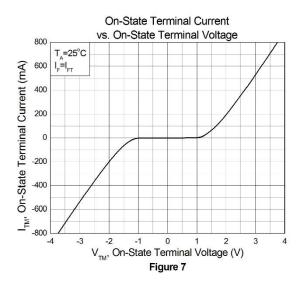


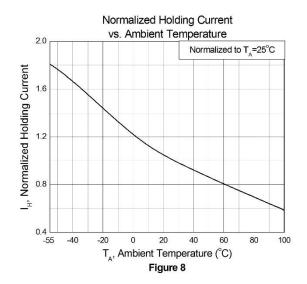


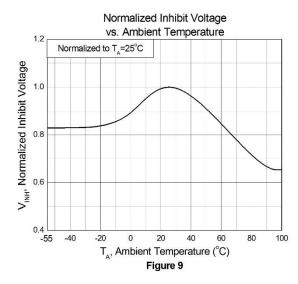




## Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified

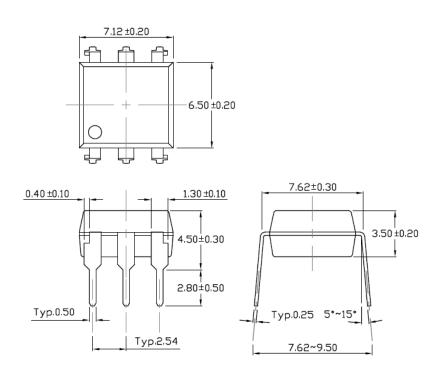




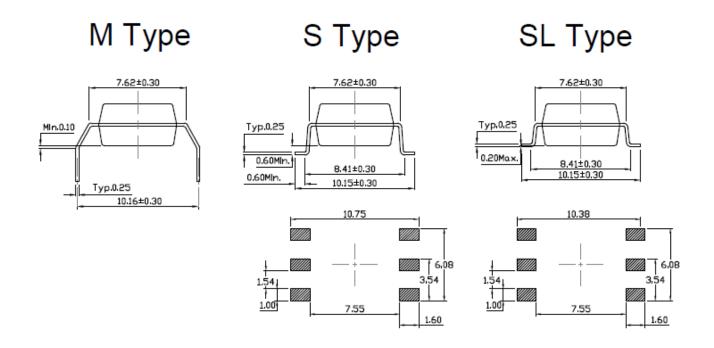




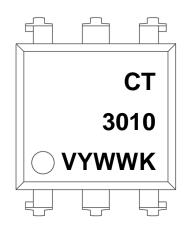
## Package Dimension Dimensions in mm unless otherwise stated



## Forming Option Dimensions in mm unless otherwise stated



## **Marking Information**



#### Note:

CT : Denotes "CT Micro"

3010 : Part Number

V : VDE Safety Mark Option (Blank or V)

Y : One Digit Year CodeWW : Two Digit Work WeekK : Manufacturing Code

## **Ordering Information**

CT303X(V)(Y)(Z), CT304X(V)(Y)(Z)

CT = Denotes "CT Micro"

303X = Part No. (CT303X:0,1,2), (CT304X:0,1,2,3)

V = VDE Safety Mark Option (Blank or V)Y = Lead Form Option (Blank, S, SL or M)

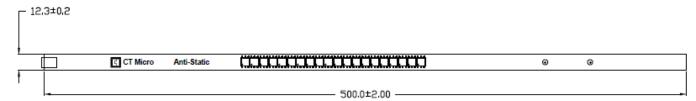
Z = Tape and Reel Option (Blank, T1, T2, T3 or T4)

G = Material Option (G: Halogen Free, Blank: Non-Halogen Free)

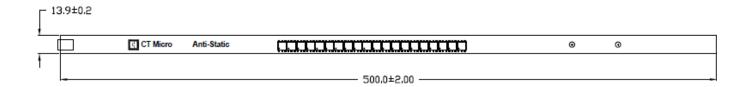
Option	Option Description	
None	None Standard 6 Pin Dip	
M	Gullwing (400mil) Lead Forming	50Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming – With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel

## Carrier Specifications Dimensions in mm unless otherwise stated

## **Tube Option Standard DIP**

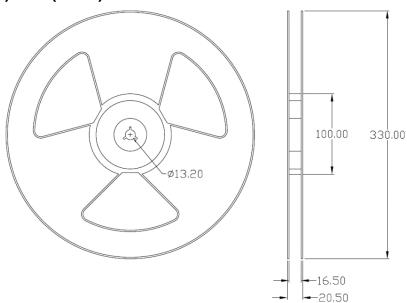


## **Tube Option M Type**



## Reel Dimension All dimensions are in mm, unless otherwise stated

## **Option S(T1/T2) & SL(T1/T2)**

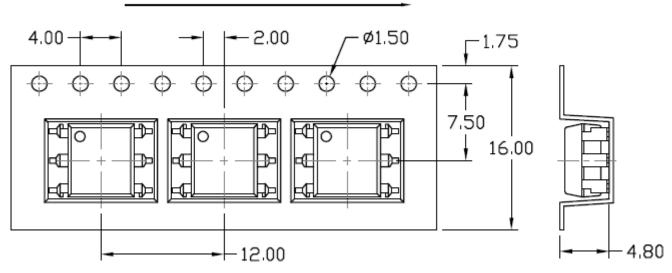




## Carrier Tape Specifications Dimensions in mm unless otherwise stated

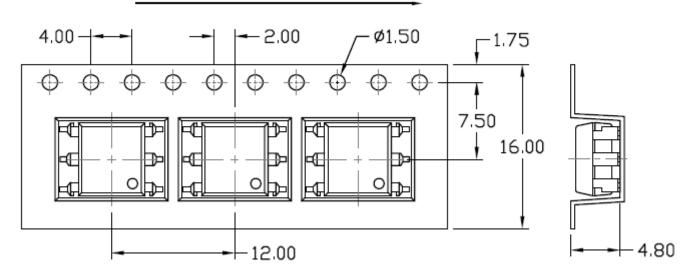
Option S (T1) & SL (T1)

# Input Direction



#### Option S (T2) & SL (T2)

## Input Direction



## Solderability spec (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

## **Wave soldering (follow the JEDEC standard JESD22-A111)**

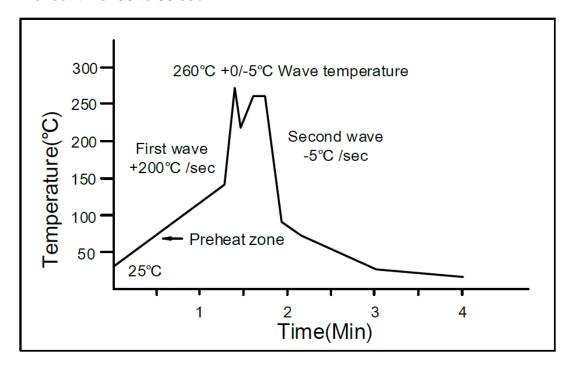
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



## Iron Soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

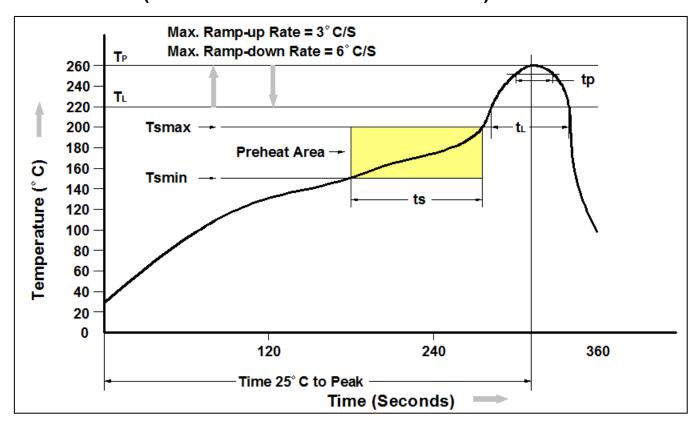
One time soldering is recommended.

Temperature: 350±10°C

Time: 5 sec max.



## Reflow Profile (follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile		
Temperature Min. (Tsmin)	150°C		
Temperature Max. (Tsmax)	200°C		
Time (ts) from (Tsmin to Tsmax)	60-120 seconds		
Ramp-up Rate (t∟ to t <sub>P</sub> )	3°C/second max.		
Liquidous Temperature (T <sub>L</sub> )	217°C		
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds		
Peak Body Package Temperature	260°C +0°C / -5°C		
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds		
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max		
Time 25°C to Peak Temperature	8 minutes max.		



#### **DISCLAIMER**

DMC-Isolator® IS A TRADEMARK OF CT MICRO INTERNATIONAL CORPORATION AND/OR ITS SUBSIDIARIES. CT MICRO OWNS THE RIGHTS TO A NUMBER OF PATENTS, TRADEMARKS, COPYRIGHTS AND OTHER INTELLECTUAL PROPERTY.

CT MICRO RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. CT MICRO DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

DISCOLORATION MIGHT OCCUP ON THE PACKAGE SURFACE AFTER SOLDERING REFLOW OR LONG

DISCOLORATION MIGHT OCCUR ON THE PACKAGE SURFACE AFTER SOLDERING, REFLOW OR LONG TERM USE. THIS DOES NOT IMPACT THE PRODUCT PERFORMANCE NOR THE PRODUCT RELIABILITY.

CT MICRO ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT EXPRESS WRITTEN APPROVAL OF CT MICRO INTERNATIONAL CORPORATION.

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instruction for use provided in the labelling, can be reasonably expected to result in significant injury to the user.
- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.